Hybrid 7p87 Traveler

March 29, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 7P87 has die: 247-123 093-114 093-116 093-118 093-119 093-120 024-047

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 7p87 classification info. Created 09:22:27 03/27/00

Hybrid 7p87 quality: fair
Chip classification: good good fair fair good good good
Bad channels: none
Bad cells: none
Random bad capacitors (chip-cell-channel): 2-34-13 2-34-15 2-34-18
   2-34-19 2-34-23 2-34-3 2-34-30 2-34-4 2-34-49 2-34-5 3-25-103
Channels at pedestal needed for DCMS: 37.7 34.8 35.6 34.7 31.8 34.6 33.7
```

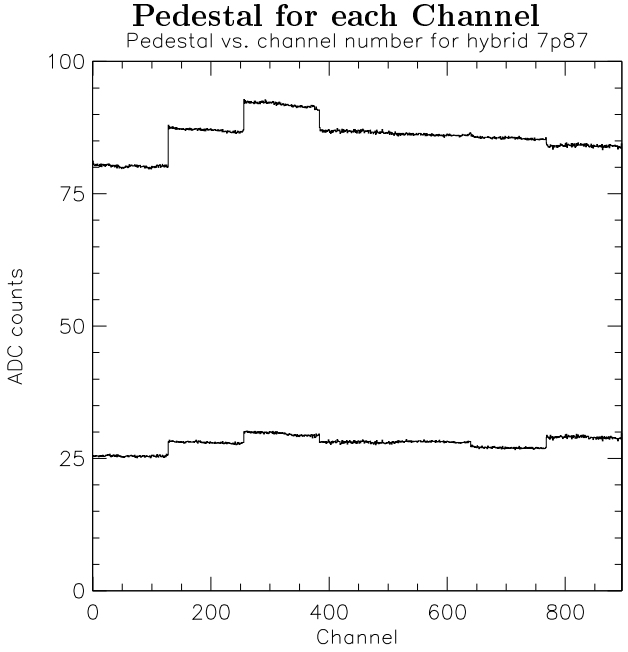
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

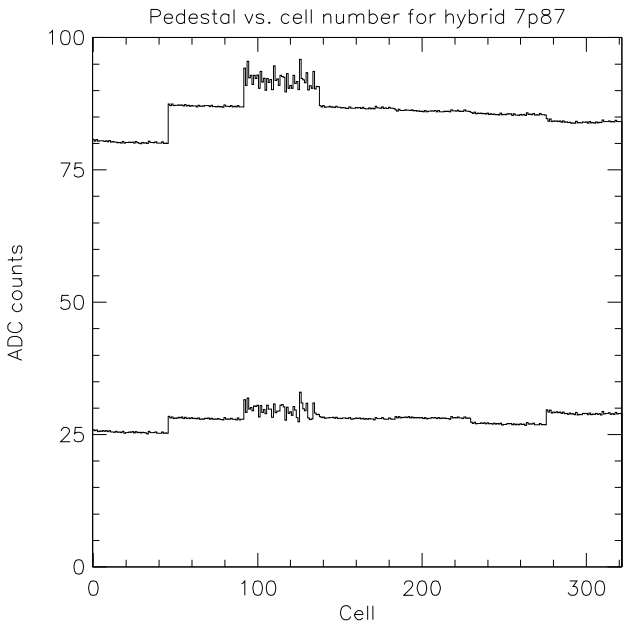
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

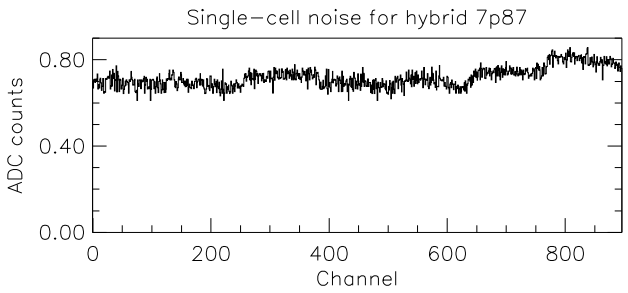
Pedestal vs. Pipeline Cell ID

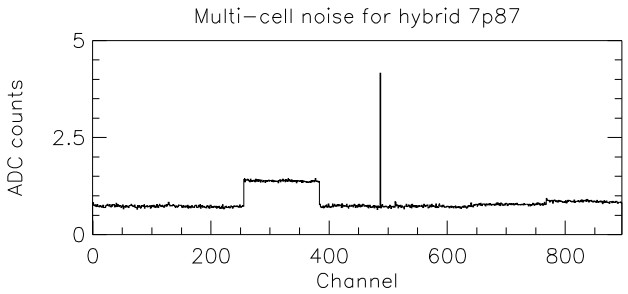


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

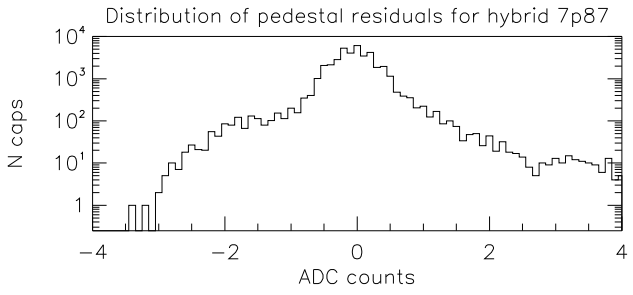
RMS Noise

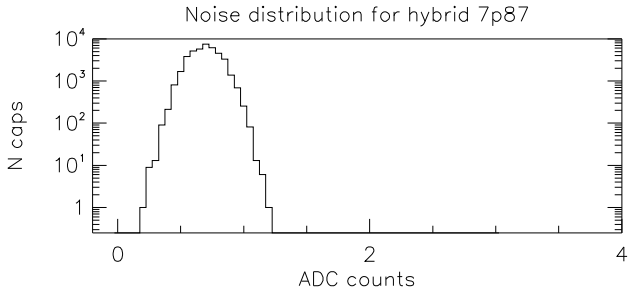




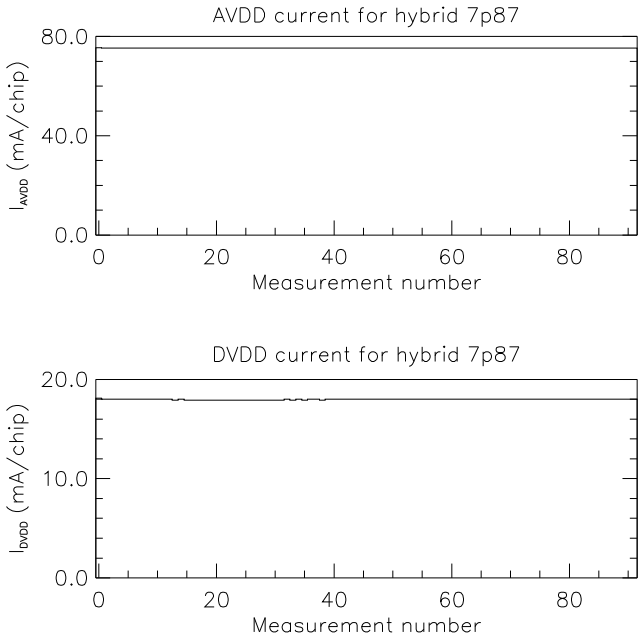
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in